

Soldered SAM data sheet SAM- λ -A- τ -4.0-12.7s-c or SAM- λ -A- τ -4.0-12.7s-e

GaAs chip area	standard:	4.0 mm x 4.0 mm
	optional:	other dimensions on request

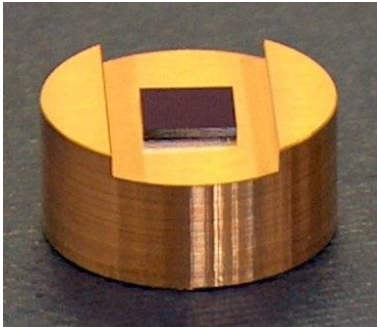
Chip thickness	standard:	450 μm
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Front side protection	the SAM is protected with a dielectric front layer.
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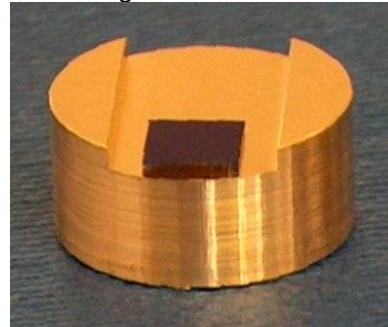
The SAM chip is soldered on a gold plated Cu-cylinder with 12.7 mm \varnothing using a Sn/Bi solder. The solder provides a low thermal resistance between the SAM and the mount.

- The **standard** position of the SAM is at the center of the mount \rightarrow x = 4.0-12.7s-c.
- **Optional** the SAM can be soldered on the edge of the mount without extra charges \rightarrow x = 4.0-12.7s-e.

Center mounted SAM



Edge mounted SAM



Mount

Cu-cylinder, \varnothing = 12.7 mm
 l = 6.0 mm